

ABSTRACT OF THE DISCLOSURE

An epoxy resin composition for semiconductor encapsulation which is for use in the resin encapsulation of semiconductor elements other than optical semiconductor elements including photoreceptors and light-emitting elements. This epoxy resin composition comprises the following ingredients (A) to (D) and has a content of ingredient (D) of 75-95% by weight based on the whole epoxy resin composition: (A) an epoxy resin, (B) a phenolic resin, (C) a specific release agent, and (D) an inorganic filler. The epoxy resin composition for semiconductor encapsulation which has improved adhesive force in application to metallic frame parts/heat radiation plates and can be inhibited from suffering separation from metallic frame parts/heat radiation plates during molding.